

4 T828 Fault Finding



Caution: This equipment contains CMOS devices which are susceptible to damage from static charges. Refer to [Section 1.2](#) in Part A for more information on anti-static procedures when handling these devices.

The following test procedures and fault finding flow charts may be used to help locate a hardware problem, however they are by no means a complete fault finding procedure. If you still cannot trace the fault after progressing through them in a logical manner, contact your nearest Tait Dealer or Customer Service Organisation. If necessary, you can get additional technical help from Customer Support, Radio Systems Division, Tait Electronics Ltd, Christchurch, New Zealand (full contact details are on page 2).

Refer to Section 5 where the parts lists, grid reference index and diagrams will provide detailed information on identifying and locating components.

The following topics are covered in this section.

Section	Title	Page
4.1	Visual Checks	4.3
4.2	Component Checks	4.3
4.3	DC Checks	4.3
4.4	RF Checks	4.4
4.4.1	General	4.4
4.4.2	PA Faults	4.4
4.5	Voltage Chart	4.5
4.6	Fault Finding Charts	4.6
4.6.1	PA	4.6
4.6.2	Power Control	4.7
4.7	Replacing RF Power Transistors	4.8
4.8	Removing The PCB From The Heatsink	4.9

Figure	Title	Page
4.1	T828 Test Break Point Location	4.4

4.1 Visual Checks

Remove the side cover from the T828 and inspect the PCB for damaged or broken components, paying particular attention to the surface mounted devices (SMDs). Also check for defective solder joints.

Refer to [Section 4.7](#), [Section 4.8](#) and [Section 3](#) of Part A for more details on repair and replacement of components.

4.2 Component Checks

If you suspect a transistor is faulty, you can assess its performance by measuring the forward and reverse resistance of the junctions. Unless the device is completely desoldered, first make sure that the transistor is not shunted by some circuit resistance. Use a good quality EVM (e.g. Fluke 75) for taking the measurements (or a 20k ohm/V or better multimeter, using only the medium or low resistance ranges).

The collector current drawn by multi-junction transistors is a further guide to their performance.

If an IC is suspect, the most reliable check is to measure the DC operating voltages. Due to the catastrophic nature of most IC failures, the pin voltages will usually be markedly different from the recommended values in the presence of a fault. The recommended values can be obtained from either the circuit diagram or the component data catalogue.

4.3 DC Checks

Note: No RF power is to be applied during these checks.

Check that +13.8V is present on the collectors of Q1, Q2, Q3 and Q4. Make this measurement when the transmitter is not keyed.

Check that +13.8V is present at pin 4 of IC1 and pin 8 of IC3.

Check that 7.0V is present at the output of regulator IC2.

4.4 RF Checks

4.4.1 General

You can measure in-circuit RF levels around Q1 and Q2 with an RF probe on which the earth lead has been shortened to a minimum (i.e. 13mm); refer to the PA Fault Finding Chart (Section 4.6.1). You must measure all other stages with a power meter at the 50Ω points in the circuit.

For problems with the power control circuitry, refer to the Power Control Fault Finding Chart (Section 4.6.2).

4.4.2 PA Faults

If a PA fault has occurred, or is suspected, it is easier to find if the various stages are isolated by use of the test breaks (refer to Figure 4.1) and each stage analysed individually. Eight 50 ohm test break points have been included throughout the RF circuitry to enable individual transistor stages to be tested.

Testing may be performed by removing the solder short across the test break and soldering a 50 ohm test lead to the appropriate signal and earth pads.

Note 1: Use good quality 50Ω coax for the "flying" test leads.

Note 2: Ensure each output is terminated in a 50Ω load of the correct power rating.

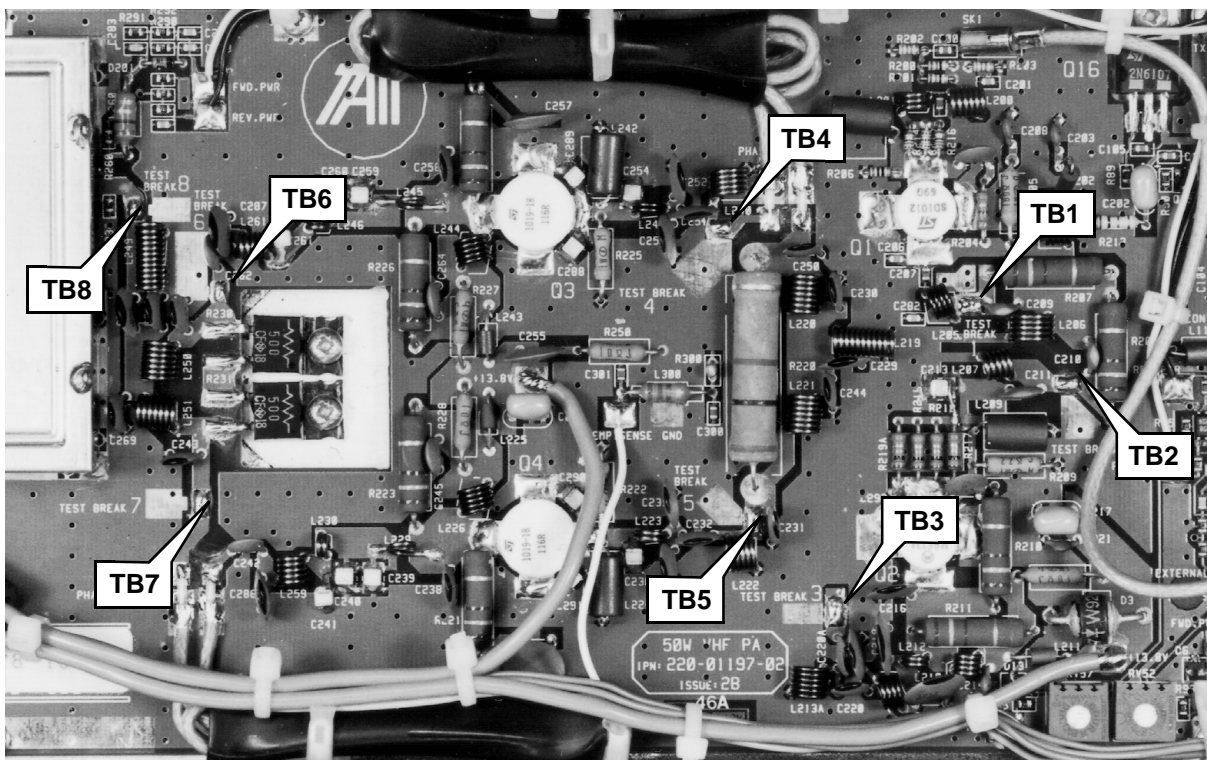


Figure 4.1 T828 Test Break Point Location

4.5 Voltage Chart

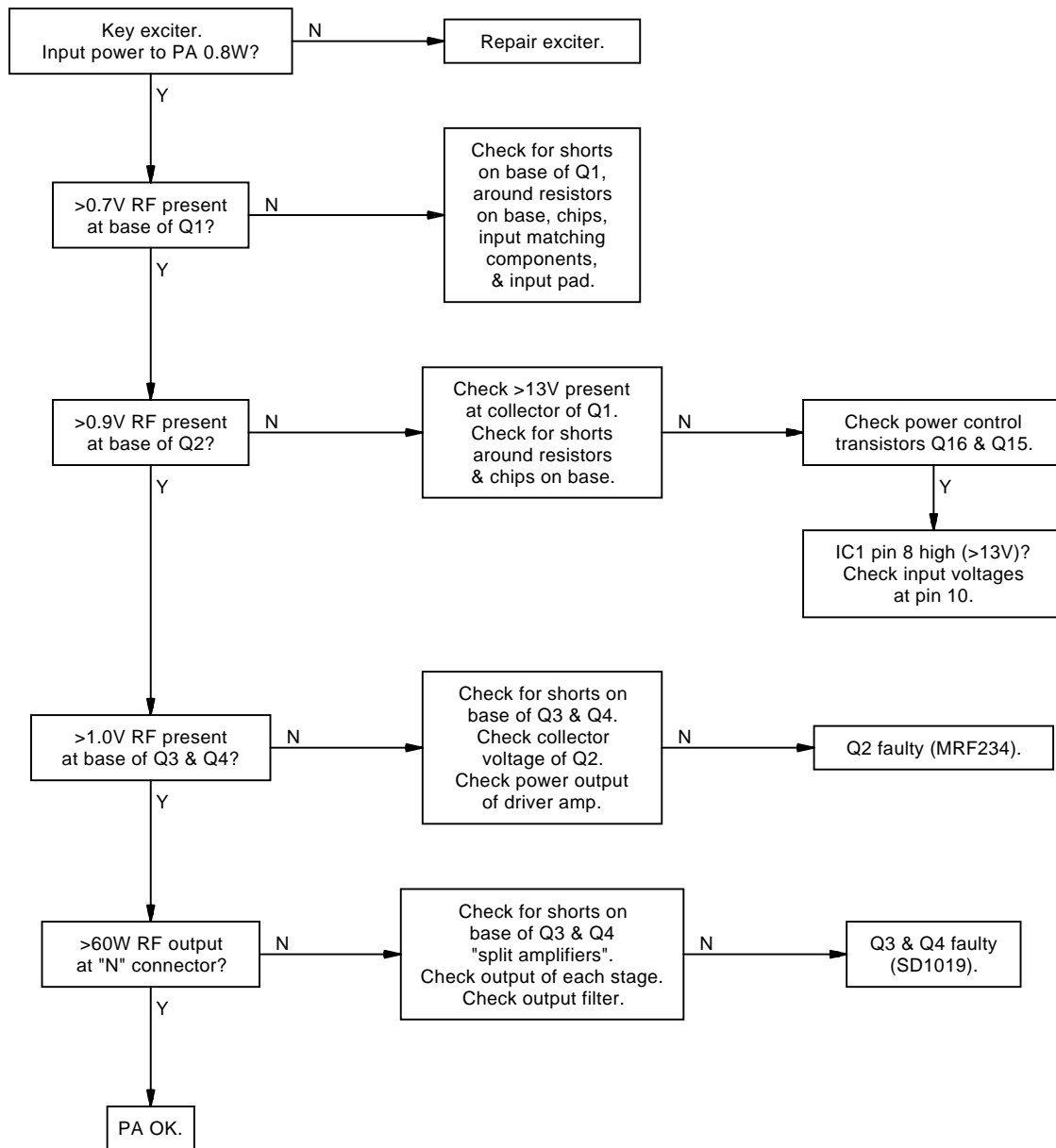
Test conditions:

- typical DC voltages measured with Fluke 77 DVM
- supply voltage 13.8V at socket
- transmitter unkeyed
- allow $\pm 20\%$ for spread of transistor characteristics.

Device	Emitter	Base	Collector
Q1	0.0V	0.0V	13.0V
Q2	0.0V	0.0V	13.8V
Q3	0.0V	0.0V	13.8V
Q4	0.0V	0.0V	13.8V
Q11	1.8V	2.2V	5.9V
Q13	0.0V	0.0V	5.9V
Q15	13.0V	13.6V	13.6V
Q16	13.8V	13.6V	13.0V

4.6 Fault Finding Charts

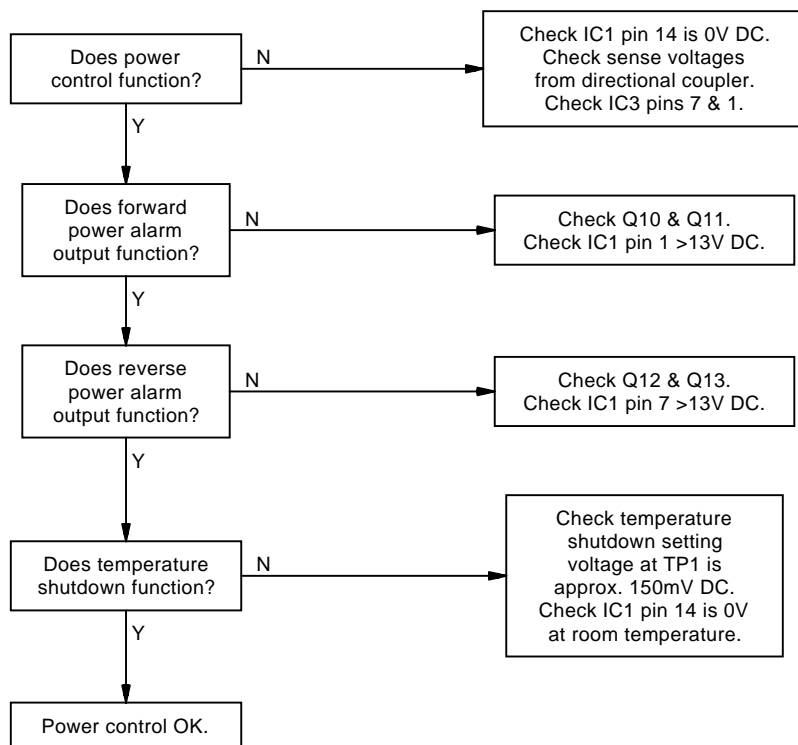
4.6.1 PA



4.6.2 Power Control

Normal operating conditions:

Measurement	Output Power	
	10W	50W
forward power at "FWD-PWR" pad (beside IC3)	1V	2.6V
reverse power at "REV-PWR" pad (beside IC3)	<10mV	50mV
IC1 pin 8	4.8V	6.8V
RV63/R64 (RV63 wiper)	7V	7V
L202	4.13V	6.2V



4.7 Replacing RF Power Transistors

**Caution:**

Failure to comply with the following procedure can result in failure of the device due to poor heatsinking, or worse, can endanger the health of the assembler if the beryllium oxide die carrier is smashed during assembly.

**Caution:**

As the location of certain components in the PA is critical to performance, it is important that any components removed or disturbed are refitted in *exactly* the same position. Before attempting to remove a transistor, note the location of any other components that will also need to be removed. Replacing each component in its original location will help to maintain the performance of the PA.

**Caution:**

Do not apply too much heat or pressure to the PCB pads and tracks as you may damage them or lift them from the PCB, causing permanent damage to the PA.

Desolder and remove the components from around the transistor.

Desolder the transistor tabs by heating with a soldering iron and lifting away from the PCB with a screwdriver or thin stainless steel spike. Unscrew the transistor stud nut and remove the device.

Remove any excess solder from the PCB pads with solder wick.

Trim the tabs of the replacement transistor so that the device sits neatly on the PCB pads provided.

Lightly tin the underside of the transistor tabs.

Apply a small amount of heatsink compound (Dow-Corning 340 or equivalent) to the transistor mounting surface. Sufficient compound should be used to ensure an even film over the entire mounting surface.

Place the transistor on the PCB in the correct orientation and ensure the tabs are flush to the surface.

Lightly solder one tab to the PCB, then torque down the retaining nut to the correct torque (0.7Nm/6in.lbf.).

**Caution:**

Do not solder all the tabs before torquing down otherwise the device may be broken.

Solder all transistor tabs to the PCB.

Replace each component in exactly the same position as noted previously.

4.8 Removing The PCB From The Heatsink

Note: This is a lengthy procedure and should be considered only after all other checks have been carried out. There are no components on the bottom of the PCB.

Remove the harmonic filter shield lid.

Remove the 50 ohm output N-type connector by unscrewing it from the heatsink casting and desoldering it from the PCB.

Unplug the 50 ohm input coaxial cable from the PCB, unscrew the BNC connector from the heatsink, and remove the connector and cable (cutting cable ties as required).

Desolder the positive and negative power feed wires from the PCB.

Desolder the alarm and metering wires from the PCB.

Remove the 2 screws securing the D-range connector and PCB to the heatsink and withdraw the assembly and wires from the heatsink (cutting cable ties as required).

Remove the transistor stud nuts.

Remove the mounting screws for the TO-220 devices: R230, R231 and Q16.

Remove the 10 PCB retaining screws.

Push the three LEDs out of their front panel grommets.

Lift the PCB gently from the heatsink to gain access to the underside of the board.

Note: R230/231 and Q1-Q4 may be stuck down with heatsink compound. You may need to carefully prise them away from the heatsink with a small screwdriver.



Caution: Keep the heatsink compound clean while the PCB is detached. Any objects caught in the heatsink compound underneath the device which prevent effective earthing and/or heatsinking may cause the device to fail.



Caution: Do not operate the PA with the PCB detached as the heatsink is used for earthing and heat dissipation.

To replace the PCB, reverse the order of removal, taking care that the wiring is correctly positioned and not 'pinched'.

Q1-Q4: Torque down the retaining nut to the correct torque (0.7Nm/6in.lbf.).

Make sure that the heatsink compound has stayed clean, and that the insulating pad for Q16 is not damaged.

If you have difficulty refitting the LEDs, try pushing the body of the LED back into the grommet with a thin screwdriver or spike.